

Notice of References Cited

 Application/Control No.
 10/626,391

 Applicant(s)/Patent Under
 Reexamination
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 Examiner
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 1722

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	IBM Technical Disclosure, vol. 30, n. 5: "Use of High Precision Silicon Molds for Replicating Microelectronic Packaging Structures"; October 1987.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
 Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.